Overview

HP Z6 G5 Workstation



- 1. Integrated Front Handle
- 2. Power Button
- 3. HDD Activity LED
- 4. Headphone/microphone combo

Front View

- 5. Front I/O Premium²:
 - 2 SuperSpeed USB Type-C[™] 20 Gbps signaling rate (USB Power Delivery 3.0),
 - 2 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A port supports BC1.2 (Battery Charging)]

Front I/O Entry:

- 4 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A ports supports BC1.2 (Battery Charging)]
- 6. SD Card Reader
- 7. 2x External 5.25" bay¹
- 8. 9.5mm Optical Drive Bay

¹Only 1 external 5.25" drive configurable from factory ²Premium Front IO is shown on photography

Overview



- 1. 1 Intel® Xeon® Processor (Sapphire Rapids)
- 8 DIMM slots for DDR5 ECC Memory

2.

- 3. •Slot 1: PCIe x16 Gen5
 - •Slot 2: PCIe x4 Gen4
 - •Slot 3: PCIe x4 Gen4
 - •Slot 4: PCIe x16 Gen4
 - •Slot 5: PCIe x16 Gen4
 - •Slot 6: PCIe x16 Gen3
- 4. 2 PCIe x4 Gen4 configurable with 2x M.2 SSDs

Internal View

- 5. 5 SATA ports
- 6. 3 Internal USB Ports. 1 single USB2.0 port, 1 dual USB2.0 port, 1 USB3.0 port (for the SD card reader).
- 7. 2 Internal 3.5" bays
- 8. 2 External 5.25" bays and Slimline Optical Drive
- 9. 2 Internal NVMe connector to front removable M.2 carrier

Overview



Rear View

- Choice of 775W, 1125W or 1450W, 90% Efficient Power Supplies
- 2. Rear Power Button
- 3. Audio in/out
- 4. Flex I/O Module (optional)

- 5. 1 RJ-45 integrated LAN port (1 GbE AMT)
- 6. 6 SuperSpeed USB Type-A 5 Gbps signaling rate
- 7. 2 10GbE LAN ports (optional)
- 8. External Antenna (optional)
- 9. Integrated Rear Handle

Form Factor

Tower

Operating Systems

Preinstalled:

- Windows 11 Pro for Workstations²
- Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade),2,3
- Ubuntu 22.04 LTS⁴
- HP Linux®-ready (minimal OS ready for customer OS installation)⁵

License Only:

 Red Hat® Enterprise Linux® Desktop Workstation (includes paper license with 1 year support; no preinstalled OS)⁶

Supported:

- Windows 11, version 22H2, 21H2²
- Windows 10, version 22H2, 21H2²
- Red Hat® Enterprise Linux® Workstation 8 & 96



Overview

- SUSE Linux® Enterprise Desktop 156
- Ubuntu 20.04 & 22.04 LTS⁵

Web-supported only:

- Windows 11 Enterprise^{2,1}
- Windows 10 Enterprise^{2,1}
- ¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.
- ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- ³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- ⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.
- ⁵A certified preloaded version of Ubuntu® 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁶For detailed Linux[®] OS/hardware support information, see: http://www.hp.com/support/linux hardware matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Processors

				Frequency Max Memory Speed (GHz) (MT/s)					
Name ¹	Cores	Threads	Base Clock Speed	Intel® Turbo Boost Max Single-Core Frequency ²	Intel® Turbo Boost Max Tech 3.0 Frequency²	Cache (MB)	1 DIMM per Channel	2 DIMM per Channel	TDP (W)
Intel® Xeon® W9-3475X	36	72	2.2	4.6	4.8	82.5	4800	4400	300
Intel® Xeon® W7-3465X	28	56	2.5	4.6	4.8	75	4800	4400	300
Intel® Xeon® W7-3455	24	48	2.5	4.6	4.8	67.5	4800	4400	270
Intel® Xeon® W7-3445	20	40	2.6	4.6	4.8	52.5	4800	4400	270
Intel® Xeon® W5-3435X	16	32	3.1	4.5	4.7	45	4800	4400	270



Overview

Intel® Xeon® W5-3433	16	32	2.0	4.0	4.2	45	4400	4400	220
Intel® Xeon® W5-3425	12	24	3.2	4.4	4.6	30	4800	4400	270
Intel® Xeon® W5-3423	12	24	2.0	4.0	4.2	30	4400	4400	220

Notes:

- Xeon W-3400 processors all feature Intel® vPro® Technology³
- Xeon W-3400 processors all support Hyper-Threading
- Xeon W-3400 processors do not offer integrated graphics

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Intel Turbo Boost Max (ITBM) performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro



Overview

Black Color **Convertibility** Nο

Expansion Slots Slot 1: PCIe x16 Gen5 (see system board •Slot 2: PCIe x4 Gen4 section for more details) •Slot 3: PCIe x4 Gen4

Slot 4: PCIe x16 Gen4 •Slot 5: PCle x16 Gen4 •Slot 6: PCIe x16 Gen3

Expansion Bays 2 internal 3.5" bays (both bays include acoustic dampening rail assemblies)

(see storage section for 2 external 5.25" bays (175mm depth limit) more details) 1 dedicated 9.5mm slim optical disk drive bay

Front I/O

Front I/O Premium: 2 SuperSpeed USB Type-C™ 20 Gbps signaling rate (USB Power Delivery 3.0), 2 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo, SD card reader

(optional). [left-most Type-A ports supports BC1.2 (Battery Charging)]

Front I/O Entry: 4 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo, SD

card reader (optional). [left-most Type-A ports supports BC1.2 (Battery Charging)]

Internal I/O [5] 3 Internal USB ports and 4 SATA ports.

Audio in/out, 6 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 RJ-45 integrated LAN ports (1 GbE AMT) Rear I/O

Optional I/O 2 10GbE LAN ports

Flex I/O Module (Serial Port v3. Dual USB-A 3.2 Gen1, USB-C 3.2 Gen2, 10GbE single port, 2.5GbE LAN

single port, 1 GbE single port, 1 GbE Fiber single port LC, WiFi6 + BT5.2 WLAN w/ INTAnt)

External Antenna

On-board RAID Support SATA RAID O Striped Array

SATA RAID 1 Mirrored Array SATA RAID 10 Striped/Mirrored SATA RAID 5 Parity Array

Chassis Dimensions

 $(H \times W \times D)$

Footprint:

H: 17.5" [444.5 mm] W: 6.65" [169 mm] D: 18.3" [465 mm]

Maximum:

H: 17.5" [444.5 mm] W: 6.65" [169 mm] D: 18.82" [478 mm] H: 24.0" [610mm]

Packaged Dimensions

W: 12.3" [313mm] D: 23.3" [593mm]

Palletization Profile

6 units x 3 layers = 18 units per pallet 1200x1000x1836mm (pallet included)

Rack Dimensions

Weight

Exact weights depend upon configuration (System weight only).

Minimum: 12.8 kg (28.2 lbs.) Typical: 14.1 kg (31.1 lbs.) Maximum:24.3 kg (53.6 lbs.)

Temperature

Operating: 5° to 40°C (40° to 104°F)1 Non-operating: -40° to 60°C (-40° to 140°F)

140°C has been validated for configs up to a 220W CPU, 2x NVIDIA® RTX A4000 graphics cards, 8x64GB

RAM, 2x 2TB M.2 storage, 2x 2TB HDD storage, and 1125W PSU

Humidity Operating: Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb



Overview

Non-operating: 10% to 90%, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non-pressurized)⁶

Operating: 3,048m (10,000ft) Non-operating: 9,144m (30,000ft)

NOTE: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1° C (1.8° F)

per 305 m (1,000 feet) elevation increase

Power Supply

Choice of 90% Efficient Power Supplies:

• 1450W • 1125W • 775W

NOTE: not all configurations are supported on all power supplies. Configuration support depends on total system power budget and having sufficient number or type of PCIe supplemental power connectors. Confirm power supply and configuration support using configurator on hp.com.

- 1450W supports up to 900W of auxiliary graphics power (dependent on system configuration).
- 1125W supports up to 600W of auxiliary graphics power (dependent on system configuration)
- 775W supports up to 230W of auxiliary graphics power (dependent on system configuration)

NOTE: updating graphics after purchase may require additional power distribution cables and/or auxiliary graphics adapters to support the new graphics configuration.

Workstation ISV Certifications Chipset See the latest list of certifications at

http://www.hp.com/united-states/campaigns/workstations/partnerships.html

Intel® W790 chipset

Memory 8 DIMM slots, supporting up to 1TB, DDR5 4800 MT/s speed depending on the system configuration



Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-3400 processors				
	Intel® Xeon® W9-3475X	Υ	N		
	Intel® Xeon® W7-3465X	Υ	N		
	Intel® Xeon® W7-3455	Υ	N		
	Intel® Xeon® W7-3445	Υ	N		
	Intel® Xeon® W5-3435X	Υ	N		
	Intel® Xeon® W5-3433	Υ	N		
	Intel® Xeon® W5-3425	Υ	N		
	Intel® Xeon® W5-3423	Υ	N		

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	1TB 7200RPM SATA 3.5in Enterprise HDD ⁵	Υ	Υ	WOR10AA
	2TB 7200RPM SATA 3.5in Enterprise HDD ⁵	Υ	Υ	2Z274AA
	4TB 7200RPM SATA 3.5in Enterprise HDD⁵	Υ	Υ	K4T76AA/AT
	8TB 7200RPM SATA 3.5in Enterprise HDD ⁵	Υ	Υ	2Z273AA
	12TB 7200RPM SATA-6G 3.5in Enterprise HDD⁵	Υ	Υ	5S461AA
	1TB 7200RPM SATA 3.5" Enterprise HDD (not-made-in-China)	Υ	N	
	2TB 7200RPM SATA 3.5in Enterprise HDD (not-made-in-China)	Υ	N	

PCIe Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number
	Z Turbo 512GB 2280 PCIe-4x4 TLC SSD	Υ	Υ	38T80AA
	Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD	Υ	Υ	38T81AA
	Z Turbo 512GB 2280 PCIe-4x4 TLC SSD (not-made-in-China)	Υ	N	
	Z Turbo 512GB 2280 PCle-4x4 TLC Z4/Z6 Kit SSD	Υ	Υ	56Q73AA
	Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	N	Υ	56Q74AA
	Z Turbo 1TB 2280 PCIe-4x4 TLC SSD	Υ	Υ	38T77AA
	Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD	Υ	Υ	38T76AA
	Z Turbo 1TB 2280 PCIe-4x4 TLC SSD (not-made-in-China)	Υ	N	
	Z Turbo 1TB 2280 PCIe-4x4 TLC Z4/Z6 Kit SSD	Υ	Υ	56Q75AA
	Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	N	Υ	5Z7E7AA
	Z Turbo 2TB 2280 PCIe-4x4 TLC SSD	Υ	Υ	38T75AA
	Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD	Υ	Υ	38T79AA
	Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	N	Υ	56Q77AA
	Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD ⁴	Υ	Υ	5S496AA/AT
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD ⁴	Υ	Υ	5S497AA/AT
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD4	N	Υ	5S4A1AA
	HP Z Turbo Drive Dual Pro			

Supported Components

HP Z Turbo Drive Dual Pro PCIe-4x4 NVMe Carrier ¹	Υ	Υ	56Q86AA
HP Z Turbo Drive Dual Pro 512GB TLC SSD	Υ	N	
HP Z Turbo Drive Dual Pro 1TB TLC SSD	Υ	N	
HP Z Turbo Drive Dual Pro 2TB TLC SSD	Υ	N	
HP Z Turbo Drive Dual Pro 4TB TLC SSD ⁴	Υ	N	
Intel® Virtual RAID on CPU (Intel® VROC) for NVMe			
Intel VROC NVMe SSD Premium Ctlr Module ²	N	Υ	3FJ81AA
Intel VROC NVMe SSD Standard Ctlr Module ³	N	Υ	3FJ80AA

Note 1: Kit includes dual pro carrier and heatsink. Requires separate purchase of Z Turbo PCIe 4x4 M.2 SSD modules.

Note 2: Enables RAID 0, 1 & 10

Note 3: Enables RAID 0, 1 & 10 plus RAID 5 with write hole closure options

Note 4: Available in June 2023

NOTE: For internal bay install, HDD option kits require separate purchase of 73P26AA HP Z6 HDD Cable Kit. For external bay install, HDD options kits require separate purchase of 73P26AA HP Z6 HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Graphics Cable	HP DisplayPort To VGA Adapter	N	Υ	AS615AA/AT	
Adapters	HP DisplayPort To VGA Adapter	N	Υ	F7W97AA	
	HP DisplayPort to HDMI Adapter	Υ	Υ	2JA63AA	
	HP (Bulk 12) miniDP-to-DP Adapter Cables	N	Υ	2KW87A6	
	HP Single miniDP-to-DP Adapter Cable	Υ	Υ	2MY05AA	
	HP miniDP-to-DP Adapter (2-pack)	Υ	N		
	HP miniDP-to-DP Adapter (4-pack)	Υ	N		
	HP miniDP-to-DP Adapter (8-pack)	Υ	N		
	HP DisplayPort To DVI Adapter (Bulk 90)	N	Υ	FH973A6	
	NVIDIA NVLink 3-Slot Bridge	Υ	Υ	340L3AA	
	NVIDIA 3D Stereo Bracket	N	Υ	KOA25AA	
	HP Graphics Power Cable CPU-8p to CPU-8p4	N	Υ	6J6H7AA	
	HP Graphics Power Cable CPU-8p to x2 PCIe 8p(6+2) ⁴	N	Υ	6J6H8AA	
Ultra High-End	NVIDIA® RTX 6000 Ada 48GB 1,3	Υ	Υ	79C23AA/AT	3
Graphics	NVIDIA® RTX A6000 48GB 1,3	Υ	Υ	2S6U3AA/AT	3
	AMD Radeon Pro W6800 32GB 1,3	Υ	Υ	340K7AA	2
	NVIDIA® RTX A5000 24GB1	Υ	Υ	20X23AA/AT	3
	NVIDIA® Quadro® Sync II	N	Υ	1WT20AA	
High-End Graphic	s NVIDIA® RTX A4500 20GB ¹	Υ	Υ	5S458AA/AT	3
	NVIDIA® RTX A4000 16GB 1,*	Υ	Υ	20X24AA/AT	3
Midrange Graphics	NVIDIA® RTX A2000 12GB ¹	Υ	Υ	5Z7D9AA/AT	3



Supported Components

	AMD Radeon RX 6700XT 12GB	Υ	N		1
	NVIDIA® T1000 8GB ²	Υ	Υ	5Z7D8AA/AT	3
	AMD® Radeon™ Pro W6600 8GB ¹	Υ	Υ	340K5AA	3
Entry Graphics	NVIDIA® T400 4GB ²	Υ	Υ	5Z7EOAA/AT	3
	AMD® Radeon™ RX 6400 4GB	Υ	Υ	6Q3U4AA/AT	1
	NVIDIA T1000 4GB ²	Υ	Υ	20X22AA/AT	3
	Intel Arc Pro A40 6GB 5	Υ	Υ	6E3Y8AA	1

^{*}Only supported with 1125W and 1450W PSUs

Note 1: Single, dual, or triple graphics configurations require the HP Z6 Fan and Front Card Guide. If configured as an after-market option, a separate purchase of the HP Z6 Fan and Front Card Guide 56Q80AA is required. If factory configured, the fan and front card guide is included.

Note 2: Dual T1000 or triple T1000 or T400 graphics configurations require the HP Z6 Fan and Front Card Guide. If configured as an after-market option, a separate purchase of the HP Z6 Fan and Front Card Guide 56Q80AA is required. If factory configured, the fan and front card guide is included.

Note 3: Dual A6000 or W6800 graphics or triple graphics configuration requires the HP Z6 PCIe Retainer with Fans. If configured as an after-market option, a separate purchase of the HP Z6 PCIe Retainer with Fans 56085AA is required. If factory configured, the PCIe retainer with fans is included.

Note 4: Required for select graphics configurations.

Note 5: Available in June 2023

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	16GB (1x16GB) DDR5 4800 DIMM ECC REG Memory (not-made-in-China)	Y	N		
	32GB (2x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	32GB (2x16GB) DDR5 4800 DIMM ECC REG Memory (not-made-in-China)	Υ	N		
	64GB (4x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	64GB (4x16GB) DDR5 4800 DIMM ECC REG Memory (not-made-in-China)	Υ	N		
	64GB (2x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	128GB (8x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	128GB (4x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	256GB (8x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	256GB (4x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	256GB (2x128GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1,2
	512GB (8x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	512GB (4x128GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1,2
	1TB (8x128GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1,2
	After Market Options				
	16GB (1x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	Υ	340K1AA	
	32GB DDR5 (1x32GB) 4800 DIMM ECC REG Memory	N	Υ	340K2AA	
	64GB DDR5 (1x64GB) 4800 DIMM ECC REG Memory	N	Υ	340K3AA	
	128GB (1x128GB) DDR5 4800 DIMM ECC REG Memory	N	Υ	69D46AA	1,2
	Note 1: This memory configuration requires the 1125 Note 2: Available in June 2023	W/1450W PSU			



Supported Components

NOTE: When configuring the system with 2 DIMMS per channel (DPC), max memory speed will decrease from 4800MHz to 4400MHz.

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Part Number
	HyperX Cloud Mix Wireless Gaming Headset	N	Υ	4P5K9AA
	HyperX Cloud Core Gaming Headset	N	Υ	4P4F2AA
	HyperX Cloud Flight Wireless Gaming Headset	N	Υ	4P5L4AA
	HyperX Cloud Stinger Core Gaming Headset	N	Υ	4P4F4AA
	HyperX SoloCast - USB Microphone	N	Υ	4P5P8AA
	Integrated Realtek ALC3205-CG Audio	Υ	N	

Optical and Removable		Factory Configured	Option Kit	Option Kit Part Number
Storage	HP CRU QX448 Removable with 200mm Cable (Qty.2) Frame/Carrier ^{1,4}	Y	Υ	56R10AA
	HP DX175 Removable HDD Frame/Carrier ^{2,4}	Υ	Υ	1ZX71AA
	HP DX175 Removable HDD Spare Carrier ^{2,4}	N	Υ	1ZX72AA
	HP CRU Secure High Performance Storage Module with 2TB M.2 SSD ³	Υ	Υ	56Q87AA
	HP CRU Secure High Performance Storage Module with 1TB M.2 SSD ³	Υ	Υ	56Q88AA
	HP CRU Secure High Performance Storage Module with 512GB M.2 SSD ³	Υ	Υ	56Q89AA
	HP 9.5mm Slim DVD-ROM Drive	Υ	Υ	K3R63AA
	HP 9.5mm Slim BDXL Blu-Ray Writer Drive	Υ	Υ	K3R65AA
	HP 9.5mm Slim SuperMulti DVD Writer	Υ	Υ	K3R64AA

Note 1: Requires separate purchase of HP CRU Secure High Performance Storage (SHIPS) Module(s).

Note 2: Only supports 4TB or lower capacity HDDs.

Note 3: HP CRU SHIPS Module Kit contains select M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX448 Frame/Carrier).

Note 4: Planned to be available in June 2023

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC ¹	Υ	Υ	436M8AA
	HP Dual Port 10GbE NIC G2	Υ	Υ	360K6AA
	Intel X550 Dual Port 10GbE NIC	Υ	Υ	1QL46AA
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA/AT
	Intel I225 Single Port 2.5GbE NIC	Υ	Υ	406L9AA
	AT-2914SX/LC-901 Single Port 1GbE NIC	Υ	Υ	1C7Q2AA
	Intel I350-T4 4-Port 1GbE NIC	N	Υ	W8X25AA
	HP Flex 10GbE Single Port	Υ	Υ	56Q71AA
	HP Flex 2.5GbE LAN Single Port	Υ	Υ	169KOAA/AT
	HP Flex 1GbE Fiber Single Port LC	Υ	Υ	20J15AA
	HP Flex 1GbE Single Port NIC	Υ	N	
	Intel® AX210 Wi-Fi 6E non-vPro + Bluetooth® 5.2 with External Antenna WLAN	Υ	Υ	340L7AA
	Intel® AX210 Wi-Fi 6 non-vPro + Bluetooth® 5.2 Flex Port NIC with	Υ	N	



Supported Components

Internal Antenna WLAN

Note1: 3rd party transceivers sold separately. You must have a transceiver installed to connect this card to a network.

Racking and Physical Security	72 Mini/72 Tower/74/76 Dopth Adjustable Fixed Pail Pack	Factory Configured N	Option Kit	Option Kit Part Number 2A8Y5AA
	Z2 Mini/Z2 Tower/Z4/Z6 Depth Adjustable Fixed Rail Rack Kit	N	ĭ	ZHOTJAH
Input Devices		Factory Configured	Option Kit	Option Kit Part Number
	HP 320K Wired Keyboard	Υ	Υ	9SR37AA/ET/UT
	HP 125 Wired Keyboard	Υ	Υ	266C9AA/ET/UT
	HP 975 USB+BT Dual-Mode Wireless Keyboard	N	Υ	3Z726AA/ET/UT
	HP 455 Programmable Wireless Keyboard	N	Υ	4R177AA/ET/UT/A6
	HP Wired Desktop 320MK Mouse and Keyboard	N	Υ	9SR36AA/ET/UT
	HP 655 Wireless Keyboard and Mouse Combo	N	Υ	4R009AA/ET/UT/A6
	HP Wired 320M Mouse	Υ	Υ	9VA80AA/ET/UT
	HP Creator 935 Black Wireless Mouse	N	Υ	1D0K8AA/ET/UT
	HP 128 LSR Wired Mouse	Υ	Υ	265D9AA/ET/UT
	HP 125 Wired Mouse	N	Υ	265A9AA/ET/UT
	HP Business Slim Smartcard Keyboard	Υ	Υ	Z9H48AA/AT

Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Flex USB-C 3.2 Gen2	Υ	Υ	141K6AA/AT
	HP Flex Dual USB-A 3.2 Gen1	Υ	Υ	141J8AA/AT
	HP Flex Serial Port v3	Υ	Υ	13L56AA/AT
	HP Dual Thunderbolt4 PCIe x4 Low Profile Card	Υ	Υ	340L1AA
	HP Type-C SuperSpeed USB 20Gbps Front IO v2 Premium Module	Υ	Υ	TBD
	HP Internal Serial+PS/2 Port	Υ	Υ	56Q78AA
	HP USB 2.0 Type-A Port Adapter Kit ³	Υ	Υ	79C24AA
	HP SD Card Reader Zx G4	Υ	Υ	2VK54AA
	HP Z6 Fan and Front Card Guide Kit⁵	Υ	Υ	56Q80AA
	HP Z6 Memory Cooling Solution ⁴	Υ	Υ	56Q82AA
	HP Z6 PCIe Retainer with Fans⁵	Υ	Υ	56Q85AA
	HP 2.5in to 3.5in HDD Adapter Kit	N	Υ	J5T63AA
	HP 2.5in HDD/SSD 2-in-1 Optical Bay Bracket	N	Υ	K4T74AA
	HP Z6 HDD Cable Kit ¹	N	Υ	73P26AA
	HP Optical Bay HDD Mounting Bracket ²	N	Υ	NQ099AA
	HP C13 1.83m Power Cord Kit (halogen-free)	Υ	N	



Supported Components

HP C13 1.83m Power Cord Kit

Y Y 6Z1T9AA

Note 1: 73P26AA HP Z6 HDD Cable Kit is required as a separate purchase for HDD option kit install into an internal bay. For external bay install, a separate purchase of 73P26AA HP Z6 HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket is required.

Note 2: NQ099AA HP Optical Bay HDD Mounting Bracket is required as a separate purchase for HDD option kits into an external bay.

Note 3: The USB 2.0 Type-A Port Adapter Kit has a single USB 2.0 type A connector.

Note 4: HP Z6 Memory Cooling Solution 56Q82AA is required as a separate purchase for after-market memory configurations using 32GB Registered DIMMs or greater. If configured from the factory, configurations using 32GB Registered DIMMs or greater will include a memory cooling solution.

Note 5: HP Z6 Fan and Front Card Guide 56Q80AA and HP Z6 PCIe Retainer with Fans 56Q85AA are required for specific graphics configurations (see Graphics section).

Software		Factory Configured	Option Kit	Support Notes
	HP Anyware	Υ	N	
	HP Performance Advisor	Υ	N	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Υ	N	2
	HP PC Hardware Diagnostics Windows	Υ	N	
	HP Wolf Security	Υ	N	3
	HP Notifications	Υ	N	
	HP Desktop Support Utility	Υ	N	
	HP Documentation	Υ	N	
	myHP	Υ	N	
	HP Easy Clean	Υ	N	
	Kingsoft WPS Office	Υ	N	4
	Z by HP Data Science Stack Manager	Υ	N	5, 6
	WSL2/Ubuntu Data Science Stack	Υ	N	5
	HP Image Assistant	N	N	
	HP Support Assistant	N	N	
	HP Smart Health	N	N	

Note 1: Supported with Windows only. Also available as a free download from

http://www.hp.com/go/performanceadvisor

Note 2: Windows OS only Note 3: Not available in Russia Note 4: Not available in China

Note 5: Only available with NVIDIA® graphics

Note 6: Only available with Ubuntu



Supported Components

Operating Systems Windows 11 Pro for Workstations^{1,2}

Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade)^{1,2,3}
Ubuntu 22.04 LTS⁴
HP Linux®-readv

¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.
² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



Supported Components

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate
 the HP Z6 G5 Workstation into the enterprise, such as PXE, remote recovery, remote
 configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates —Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Class 3 UEFI specification version 2.7
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery. Additional HP BIOS Features:
 - Power-On password Helps prevent an unauthorized user from powering on the system.
 - Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
 - S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - Power to expansion connectors / slots
 - Most Wake events other than power buttons and WOL (Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - USB charging ports

HP Sure Start Gen7

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is
 executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown
 and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is
 policy driven for better manageability. Start is set by default to automatically repair the BIOS
 if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating.



Supported Components

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen6¹³
HP DriveLock & Automatic DriveLock
BIOS Update via Network
Master Boot Record Security
Power On Authentication
Absolute Persistence Module²³
Pre-boot Authentication
HP Wireless Wakeup

Software

HP Desktop Support Utility HP Performance Advisor¹ HP Privacy Settings HP Notifications myHP

Manageability Features

HP Driver Packs²
HP System Software Manager (SSM)
HP BIOS Config Utility (BCU)
HP Client Catalog
HP Manageability Integration Kit Gen6³

Client Security Software

HP Wolf Security (Including HP Sure Click & HP Sure Sense)²² HP Pro Wolf Security (Including Credential Manager)¹⁸ HP Client Security Manager Gen 7⁴ HP Sure Run⁹ HP Sure Recover¹⁰ HP Power On Authentication Microsoft Defender⁷

Security Management

HP Security Update Service (SUS)
Secure Erase¹⁶
TPM 2.0 Embedded Security Chip(Common Criteria EAL4+ Certified)²⁴
SATA port disablement (viaBIOS)
Serial, USB enable/disable (viaBIOS)
Power-on password (viaBIOS)
Setup password (viaBIOS)
Support for chassis padlocks and cable lock devices
Integrated hood sensor0
HP Sure Start Gen48

- ¹ HP Performance Advisor Software HP Performance Advisor is ready to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor
- ² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- ³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- ⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.



Supported Components

- ⁷ Microsoft Defender Opt in and internet connection required for updates.
- ⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.
- ⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
- ¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- ¹³ HP BIOSphere Gen6 features may vary depending on the platform and configurations.
- ¹⁶ Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane.
- ¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated carrier purchased to the terms contained in this EULA the license for the HP Wolf Pro Security Edition (HP Suppose Pro and
- earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.
- ²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features
- ²³ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- ²⁴Firmware TPM is version 15.21. Hardware TPM is v2.0.



System Technical Specifications

System Board

System Board Form

Factor

Approximately 284.48mm x 297.18mm (11.2x11.9 inches).

Processor Socket Single LGA-4677 **CPU Bus Speed** DMI Gen4 x 8 lanes

Chipset Intel W790 Alder Lake - WS PCH

Super I/O Controller Nuvoton SIO21

Memory Expansion Slots 8 DDR5 memory slots

Memory Type Supported DDR5 RDIMMs (Registered), RDIMMs and 3DS RDIMMs

Memory Modes Memory Speed Supported

Non-Interleaving for single channel. Interleaving when multiple channels are populated

4800MT/s for 1DPC and 4400MT/s for 2DPC; DDR5

Memory Protection ECC on data

Maximum Memory 1TB

Memory Configuration

16GB, 32GB, 64GB RDIMMs and 128GB 3DS RDIMMs are supported.

RDIMMs and 3DS RDIMMs cannot be mixed in the same system. 64GB RDIMMs cannot be mixed with

other capacities in the same system.

NVDIMM Memory

(Supported)

PCI Express Connectors

Standard PCIe Slots:

•1 PCI Express Gen5 slot x16 mechanical/ x16 electrical (full height, full length) 2 PCI Express Gen4 slot x16 mechanical/ x16 electrical (full height, full length) • 2 PCI Express Gen4 slot x4 mechanical/ x4 electrical (full height, half length)

• 1 PCI Express Gen3 slot x16 mechanical/x8 electrical (full height, full length)

M.2 Slots:

No

• 2 PCI Express Gen4 slot x4.

Other PCIe Connections:

 2 Front NVMe Storage (SlimSAS PCIe Gen4 x8) (each PCIe connection supports two x4 M.2 devices for a total system support of four x4 M.2 devices via QX448)

• 1 10GbE (PCIe Gen3 x4)

Supported Drive Interfaces

SATA Number of SATA ports: 5

Intel® SATA controller: primary SATA

Integrated RAID On-board RAID Support

Intel® VROC® SATA RAID 0, 1, 5, and 10 supported on Windows 10 and

11. RHEL 8.6 and later. SLE 15 SP4 and later

Intel® VROC® NVMe RAID 0, 1, 5, and 10 supported with presence of appropriate VROC upgrade module (after-market kits) on Windows 10

and 11, RHEL 8.6 and later, SLE 15 SP4 and later

Factory Configured RAID: None

Integrated Graphics No

Network Controller WGI219LM.

WGI219LM LOM provides Management capabilities: WOL, PXE 2.1,

DASH 1.1 and AMT

External SATA (eSATA) Nο

Serial 1 internal header (requires optional Serial Port Adapter Kit)

2nd Serial No **HD Integrated Audio** Yes



System Technical Specifications

USB Connector(s) Front I/O Entry: **Front**

4 USB 3.1 Gen1 Type-A (left-most port supports Battery Charging 1.2)

Front I/O Premium:

2x USB 3.2 Gen2x2 Type-C™ (Power Delivery 3.0)

2x USB 3.1 Gen1 Type-A (left-most port supports Battery Charging

1.2)

• USB Type-C Ports provide 3 Amps @ 5 Volts

• Charging USB Type-A port provides 1.5 Amps @ 5 Volts • Standard USB Type-A Ports provide 900mA @ 5 Volts

4x USB 3.1 Gen1 Type-A with USB hub and 2x USB 3.2 Gen 1 Type-A Rear

without hub.

(Optional: 2x USB 3.0 Type-A (optional via Flex module) or 1x USB 3.1

Gen2 Type-C charging port (optional via Flex module).

1 USB 3.2 Gen1 header, with a single 12-pin shrouded connector. This Internal

header supports a USB Media Card reader.

1 USB 2.0 single port header 1 USB 2.0 dual port header

Flash ROM Yes **CPU Fan Header** Yes

Memory Fan Header Yes (dual header)

Chassis Fan Header 1 front, one rear and one Aux Fan Header (dual)

Front PCI Fan Header Yes (connects to AUX fan header) Yes

Front Control

Panel/Speaker Header

CMOS Battery Holder -Yes

Lithium

Integrated Trusted Integrated TPM 2.0.

Platform Module Convertible to FIPS 140-2 Certified Mode through firmware v15.21.

The TPM module is disabled where restricted by law.

Power Supply Headers Yes Power Switch, Power LED Yes & Hard Drive LED Header **Clear Password Jumper** Yes

Keyboard/Mouse USB and PS/2 (option)

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 11 Professional 64 bit, Red Hat Linux 64-bit.

²M.2 storage supports compatible devices up to 80mm

System Technical Specifications

System Configuration	ns						
Example Configuration	Processor Info	Intel® Xeon® \	N5-3423 12C 2	2.1GHz 4800 2	20W		
#1	Memory Info	32GB DDR5 (2	x16GB) RegRA	M			
	Graphics Info	1x NVIDIA® AZ	2000				
	Disks/Optical/Floppy	1x 4TB Intern	al M.2 SSD + 1	k DVDRW SATA	1		
	PSU	775W					
	Other	N/A					
Energy Consumption (Watts)		115	VAC	230	VAC	100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	103.608	101.857	103.956	102.238	103.159	101.483
	Windows Busy Typ (S0)	305	.875	301.956		304.253	
	Windows Busy Max (S0)	337	.145	329	.662	337.118	
	Sleep (S3)	3.624	3.614	3.628	3.617	3.621	3.608
	Off (S5)	2.136	2.143	2.165	2.146	2.158	2.138
	Zero Power Mode (EuP)	0.238		0.288		0.237	

Heat Dissipation		115	VAC	230	VAC	100 VAC		
(Btu/hr)		LAN	LAN	LAN	LAN	LAN	LAN	
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled	
	Windows Idle (S0)	353.577	347.536	354.697	348.836	351.978	346.261	
	Windows Busy Typ (S0)	1043.646		1030	0.274	1038	3.111	
	Windows Busy Max (S0)	1150).339	1124	1.807	1150).247	
	Sleep (S3)	12.365	12.331	12.378	12.341	12.354	12.311	
	Off (S5)	7.381	7.311	7.386	7.322	7.363	7.294	
	Zero Power Mode (EuP)	0.8	0.812 0.982 0.808					
Example Configuration	Processor Info	Intel® Xeon® W5-3433 16C 2.0GHz 4800 220W						
#2	Memory Info	64GB DDR5 (4	x16GB) RegRA	λM				
	Graphics Info	1x NVIDIA® A4	1000					
	Disks/Optical/Floppy	1x 1TB Internal SATA HDD + 2x 4TB Internal M.2 SSD + 1x DVDRW SATA						
	PSU	775W						
	Other	N/A						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	117.751	114.977	117.982	115.689	116.598	116.482	
	Windows Busy Typ (S0)	382	.156	378	.561	380	.263	
	Windows Busy Max (S0)	400	.368	396	.988	398	.233	
	Sleep (S3)	4.221	4.138	4.286	4.236	4.211	4.203	
	Off (S5)	2.246	2.238	2.315	2.305	2.226	2.211	
	Zero Power Mode (EuP)	0.2	241	0.2	291	0.2	237	

Heat Dissipation	115	VAC	230	VAC	100	VAC
(Btu/hr)	LAN	LAN	LAN	LAN	LAN	LAN



System Technical Specifications

		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled	
	Windows Idle (S0)	401.766	392.301	402.554	394.731	397.832	397.436	
	Windows Busy Typ (S0)	1303	3.916	129	1.65	1297	'.457	
	Windows Busy Max (S0)	1366	5.056	1354	1354.523		3.771	
	Sleep (S3)	14.402	14.118	14.623	14.453	14.367	14.341	
	Off (S5)	7.663	7.636	7.898	7.864	7.595	7.543	
	Zero Power Mode (EuP)	0.8	322	0.9	92	0.8	808	
Example Configuration	Processor Info	Intel® Xeon® W7-3445 20C 2.6GHz 4800 270W						
#3	Memory Info	128GB DDR5	(8x16GB) RegF	RAM				
	Graphics Info	2x NVIDIA® A4	1000					
	Disks/Optical/Floppy	2x 1TB Intern	al SATA HDD +	2x 4TB Interna	al M.2 SSD + 1>	DVDRW SATA		
	PSU	1125W						
	Other	N/A						

Energy Consumption		115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	143.728	141.622	144.552	142.138	142.115	142.023
	Windows Busy Typ (S0)	529.174		524.226		528.456	
	Windows Busy Max (S0)	647.546		639.41		646.234	
	Sleep (S3)	5.617	5.438	5.686	5.592	5.601	5.318
	Off (S5)	2.438	2.417	2.513	2.468	2.429	2.386
	Zero Power Mode (EuP)	0.246		0.296		0.244	

Heat Dissipation		115	VAC	230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
		Enabled	Disableu	Enabled	Disabled	Enabled	Disabled
	Windows Idle (S0)	490.399	483.214	493.211	484.974	484.896	484.582
	Windows Busy Typ (S0)	1805	.542	1788.659		1803.092	
	Windows Busy Max (S0)	2209	.426	2181	.687	2204	.951
	Sleep (S3)	19.165	18.554	19.401	19.079	19.111	18.145
	Off (S5)	8.318	8.246	8.574	8.421	8.287	8.141
	Zero Power Mode (EuP)	0.8	39	1.0	09	0.8	32

Example Configuration	Processor Info	Intel® Xeon® W7-3455 24C 2.5GHz 4800 270W
#4	Memory Info	256GB DDR5 (8x32GB) RegRAM
	Graphics Info	2x NVIDIA® A6000
	Disks/Optical/Floppy	2x 4TB Internal SATA HDD + 1x 4TB Internal M.2 SSD + 1x DVDRW SATA
	PSU	1450W/200V
	Other	N/A

Energy Consumption		115	VAC	230 VAC		100 VAC	
(Watts)		LAN Enabled LAN Disabled L		LAN Enabled	LAN Disabled	LAN Enabled LAN Disabled	
	Windows Idle (S0)	N,	/A	165.724 158.644		N/A	
	Windows Busy Typ (S0)	N/A		724.391		N/A	

System Technical Specifications

Windows Busy Max (S0)	N/A		1092	1092.632		N/A	
Sleep (S3)	N/A	N/A	6.458	6.157	N/A	N/A	
Off (S5)	N/A	N/A	4.623	4.428	N/A	N/A	
Zero Power Mode (EuP)	N.	/A	2.2	:68	N.	/A	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	N	/A	565.451	541.293	N.	/A
	Windows Busy Typ (S0)	N	/A	2471	.622	N.	/A
	Windows Busy Max (S0)	N/A		3728.061		N/A	
	Sleep (S3)	N/A	N/A	22.682	21.007	N/A	N/A
	Off (S5)	N/A	N/A	15.804	15.108	N/A	N/A
	Zero Power Mode (EuP)	N	/A	7.7	'38	N,	/A

NOTE: The numbers in this table are from actual measurements on a single system. There will be some variation from unit to unit.

NOTE: The busy power number and associated BTU/hr number for each configuration will be a strong function of the actual application software run on the system. There can be a great deal of variation in this number.

NOTE: The Power Supply Efficiency report may be found at the following links:

https://www.pluqloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

System Technical Specifications

Operating Voltage Range 90-269 VAC **Rated Voltage Range** 100-240 VAC **Rated Line Frequency** 50-60 Hz Operating Line Frequency 47-66 Hz

Range

ENERGY STAR® certified Yes

(Config Dependent)

Yes

Yes

Yes

FEMP Standby Power

CECP Compliant @ 220V

Yes, with Wake-on-LAN disabled: <1W in S5 - Power Off

Compliant

Built-in Self Test (BIST)

LED

Surge Tolerant Full Ranging Power Supply

(withstands power surges

up to 2000V)

Hood Lock Header Yes ErP Lot 6- Tier 1 Yes Compliance @ 230V (<1W

in S5 - Power Off)

ErP Lot 6- Tier 2 Yes Compliance @ 230V

(<0.5W in S5 - Power Off)

-		and High-end configurations; tested on floor)			
System Configuration	110000001 11110	1x Intel Xeon w5-3423 12C 2.1GHz 4800 220W			
(Entry level)	Memory Info	64GB (4x16GB) DDR5 4800MHz RDIMM			
	Graphics Info	1xNVIDIA RTX A2000			
	Disks/Optical	1x Internal 4TB M.2+ 1xDVDRW SATA			
	Power Supply	775W			
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)		
	Idle	3.3	15		
	Hard drive Operating (Drive Random Seek)	3.4 15			
	Active mode	3.3	15		
System Configuration	Processor Info	1x Intel Xeon w-3445 20C 2.6GHz 4800 270W			
(Mid-level)	Memory Info	128GB (8*16GB) DDR5 4800MHz RDIMM			
	Graphics Info	1xNVIDIA RTX A4000			
	Disks/Optical	1x1TB HDD + 1xInternal 4TB M.2 SSD + 1xDVDRW SATA			
	Power Supply	775W			
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)		
	Idle	3.1	16		
	Hard drive Operating (Drive Random Seek)	3.4 22			



System Technical Specifications

	Active mode	3.4	21		
System Configuration	Processor Info	1x Intel Xeon w-3465X 28C 2.5GHz 4800 300W			
(High-end)	Memory Info	512GB (8x64GB) DDR5 4800MHz RDIMM			
	Graphics Info	3x NVIDIA RTX A6000			
	Disks/Optical	2x4TB HDD + 2xInternal 4TB M.2 SSD + 1xDVDRW SATA			
	Power Supply	1125W			
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)		
	Idle	3.8	21		
	Hard drive Operating (Drive Random Seek)	3.9	24		
	Active mode	4.7	29		

Environmental Requirements **Temperature** Operating: 5° to 40°C (40° to 104°F)¹

Non-operating: -40° to 60°C (-40° to 140°F)

¹40°C has been validated for configs up to a 220W CPU, 2x NVIDIA® RTX A4000 graphics cards, 8x64GB RAM, 2x 2TB M.2 storage, 2x 2TB HDD

storage, and 1125W PSU

Humidity Operating: 8% to 85% RH, non-condensing

Non-operating: 8% to 90% RH, non-condensing

Maximum Altitude Operating: 3,048 m (10,000 feet)

Non-operating: 9,144 m (30,000 feet)

Dynamic Shock

Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20g

NOTE: Values represent individual shock events and do not indicate

repetitive shock events

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to $0.0025g^2/Hz$ Non-operating random: 2.0g (rms), 5-500 Hz, up to $0.0150 g^2/Hz$

NOTE: Values do not indicate continuous vibration.

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1°C (1.8°F) for every 305 m (1,000 feet) increase in elevation,

up to 3048 m (10,000 feet)



System Technical Specifications

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information

Optical Drive Tool-less, 2nd Optical Drive requires a 5.25" bay carrier

Hard Drives Tool-less **Expansion Cards** Tool-less

Processor Socket Screw-in processor coolers

Blue User Touch Points Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes

and Connectors

Memory Tool-less **System Board** Screw-in Yes

Power and HD LED on Front of Computer

Over-Temp Warning on

Yes

Dual Function Front

Power Switch

Yes, causes a fail-safe power off when held for 4 seconds

Padlock Support Yes (optional): Locks side cover and secures chassis from theft 7.0 mm (0.2756 in) diameter padlock

loop at rear of system

Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm **Cable Lock Support**

slot at rear of system

Universal Chassis Clamp

Lock Support

Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multiple units to be chained together when used with optional cable with threaded feature at rear of

system

Chassis Interlock Sensor Yes

Sensor detects when the access panel has been removed. The access panel must be installed for the

system to power ON. Removal of the access panel during operation will power OFF the system.

Solenoid Lock and Hood

Sensor

Yes (optional)

The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through

software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed

Rear Port Control Cover No Serial, USB, Audio, Yes

Network. Enable/Disable

Port Control

Removable Media Write/Boot Control Yes

Power-On Password Yes

Setup Password Yes, prevents an unauthorized person from changing the workstation configuration.

3.3V Aux Power LED on

System PCA

No

NIC LEDs (integrated) (Green & Amber)

Yes

CPUs and Heatsinks

A torx driver (T30) is needed to remove the processor heatsink. CPU attached to heatsink via tool-less

clip

Power Supply Diagnostic Yes

Front Power Button Yes



System Technical Specifications

Yes, white (normal), red (fault) Front Power LED

Front Hard Drive Activity Yes

LED

Front ODD Activity LED Yes. on device

Internal Speaker System/Emergency ROM Yes

Flash Recovery

Cooling Solutions Air cooled forced convection

Power Supply Fans 80 mm x 80 mm x 25 mm (non-serviceable)

CPU Heatsink Fan 108 mm x 108 mm x 25 mm **Chassis Fan** Rear: 120 mm x 120mm x 25 mm

Front (optional): 120 mm x 120 mm x 25 mm

PCIe Retainer (optional based on configuration): Dual 80 mm x 80 mm x 20 mm Dual 60 mm x 60 mm x 25 mm Blindmate (optional based on configuration)

HP PC Hardware Diagnostics UEFI

Memory Heatsink Fan

Yes

Access Panel Key Lock Yes, side panel barrel keylock (optional from the factory only) **ACPI-Ready Hardware** Advanced Configuration and Power Management Interface (ACPI).

• Allows the system to wake from a low power mode.

Controls system power consumption, making it possible to place individual cards and peripherals in a

low-power or powered-off state without affecting other elements of the system.

Integrated Chassis

Handles

Yes, Front handle and dedicated rear recess

Power Supply Requires T15 Torx or flat blade screwdriver

PCI Card Retention Yes, rear (all), middle (all), front (full-length cards with extender, using Fan and Front Card

Guide Kit)

Flash ROM **Diagnostic Power Switch** Yes

LED on board

Yes

Clear Password Jumper Yes **Clear CMOS Button** Yes CMOS Battery Holder Yes

DIMM Connectors Yes

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering, 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider. and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic



System Technical Specifications

location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- **ENERGY STAR, California Energy Commission (CEC)**
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety guestions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex r135 uk/en/any/corp/hpukmu_chev/certificates)
- **GS** Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- **CCC Certificates**
- **Ergonomics**

Please contact techregshelp@hp.com

BIOS

PCIe 5.0 Support Full BIOS support for PCI Express through industry standard interfaces. Supported speeds and slot

information vary.

ATA/ATAPI AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is **WMI Support**

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

Users can define a specific date and time for the system to power on. **BIOS Power On**

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Flash Recovery with

Video **Replicated Setup** Recovers system BIOS in corrupted Flash ROM.

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

SMBIOS System Management BIOS Reference Specification, Version 3.2

Boot Control Disables the ability to boot from removable media on supported devices.

Memory Change Alert Alerts management console if memory is removed or changed. **Thermal Alert** Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

• ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.



System Technical Specifications

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console.

ACPI (Advanced Allows the system to enter and resume from low power modes (sleep states).

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Management Interface) Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

Ownership Tag A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Shutdown

Instantly Available PC

(Suspend to RAM - ACPI sleep state \$3)

Remote System Installation via F12 (PXE operating system.

2.1) (Remote Boot from Server)

ROM revision levels

System board revision

level Start-up Diagnostics (Power-on Self-Test)

Auto Setup when new hardware installed

Localized ROM Setup

Asset Tag Per-slot Control

Adaptive Cooling

Pre-boot Diagnostics UEFI Specification

Revision

ACPI

CD Boot

EHCI

PCI Express

SATA

SPD

TPM

UHCI **USB**

Allows for very low power consumption with quick resume time.

Allows a new or existing system to boot over the network and download software, including the

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup), Version is

available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

Allows management SW to read revision level of the system board.

Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with

local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory.

Allows I/O slot parameters (option ROM enable/disable, bifurcation, speed) to be configured

individually.

Control parameters are set according to detected hardware configuration for optimal acoustics.

(Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7

Advanced Configuration and Power Management Interface, Version 6.0

"El Torito" Bootable CD-ROM Format Specification Version 1.0 Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0

PCI Express Base Specification, Revision 4.0 PCI Express Base Specification, Revision 5.0 Serial ATA Specification, Revision 1.0a

Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5

Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0 JEDEC JESD300-5

Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9672).

Common Criteria EAL4+ certified. FIPS 140-2 Certification

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

Universal Host Controller Interface Design Guide, Revision 1.1

Universal Serial Bus Revision 1.1 Specification

System Technical Specifications

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification USB Battery Charging specification, Revision 1.2 USB Power Delivery specification Revision 3.0

SMBIOS System Management BIOS Reference Specification, Version 3.2

Social and Environmental Responsibility

Eco-Label Certifications & Declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered worldwide
- TCO Certified
- China Energy Conservation Program (CECP)

Sustainable Impact Specifications

- Ocean-bound plastic in system fans
- 40% post-consumer recycled plastic
- Contains 10% post-industrial recycled metal
- Internal Power Supply 90% efficient

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data is based on a "Typically Configured Desktop Workstation".

Energy Consumption (in accordance with US ENERGY STAR® test

method)	115VAC, 60Hz	230VAC, 50Hz	
Normal Operation (Sort idle)	119.10 W	120.50 W	
Normal Operation (Long idle)	117.94 W	118.45 W	
Sleep	3.97 W	4.03 W	
Off	2.32 W	2.42 W	

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz
Normal Operation (Short idle)	406.13 BTU/hr	410.91 BTU/hr
Normal Operation (Long idle)	402.18 BTU/hr	403.91 BTU/hr
Sleep	13.54 BTU/hr	13.74 BTU/hr
Off	7.91 BTU/hr	8.25 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions Sound Power Sound Pressure

System Technical Specifications

Longevity and

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features

(in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)	(L _{pAm} , decibels)	
Typically Configured – Idle	3.1	16	
Drive Random Seek	3.4	22	
Active Mode	3.4	21	



System Technical Specifications

Upgrading

and/or components contained in the product may include:

- 3 USB ports
- 1 PC card slot (type I/II)1 ExpressCard/54 slot
- 1 IEEE 1394 Port
- 2 SODIMM memory slots
- Optional expansion base docking station
- 1 multi-bay II storage port
- Interchangeable HDD

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery in this product complies with EU Directive 2006/66/EC

Battery size: CR2032 (coin cell) Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40 ppm by weight

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94.8% recycle-able when properly disposed of at end of life.

Packaging Materials External: PAPER/Corrugated At least 35% Recycled

PAPER/Molded Pulp 100% Recycled

Internal: PLASTIC/Polyethylene low 80% Recycled

density - LDPE

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

System Technical Specifications

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these quidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who



System Technical Specifications

integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

Manageability

Industry Standard Specifications Intel® Active Management Technology (AMT)

This product meets the following industry standard specifications for manageability functionality:

DASH 1.2 (via Intel® LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 16.10

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 16.10 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back



System Technical Specifications

- Local Time Sync to UTC

• Remote Memory Dump Command – Creates memory dump for debug Intel® vPro™ Technology Yes, when configured with an Intel® vPro™ supporting processor.



Technical Specifications - Stable & Consistent Offerings

Stable & Consistent Offerings

Global Series SKUs

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

Stable & Consistent Offerings

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no

special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors

Product Offering

#

6M6S5AV Intel Xeon W5-3425 6M6S7AV Intel Xeon W5-3435X

Graphics

Product Offering

#

695F4AV AMD Radeon RX 6400 57D43AV AMD Radeon Pro 6600

Storage

Product Offering

#

57F29AV Z Turbo 1TB PCIe-4x4 2280 TLC M.2 Solid State Drive

57D76AV

1TB 7200RPM SATA 3.5in Enterprise



Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

Performance PCIe SSDs for HP Workstations Z Turbo 512GB 2280 PCIe-4x4 TLC SSD Capacity 512GB
Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

PCI Express 4.0 x4 electrical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read ut

No

Sequential Read up to 6400MB/s*
Sequential Write up to 3400MB/s*
Random Read up to 600K IOPS*
Random Write up to 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Nο

Performance Sequential Read up to 6400MB/s*

Sequential Write up to 3400MB/s*
Random Read up to 600K IOPS*
Random Write up to 600K IOPS*

Self-Encrypting Drive OPAL 2

Support

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module Capacity1TBProtocolPCleForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours



^{*}Actual performance may vary.

^{*}Actual performance may vary.

up to 6500MB/s*

QuickSpecs

Technical Specifications - Hard Drives

Rated for 24/7/365

operation

Nο

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD Capacity **Protocol PCIe Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

400TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD

Capacity 1TB **PCIe Protocol Form Factor** M.2 **Controller** NVMe **NAND Type** 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD

21B
PCIe
M.2
NVMe
3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

Nο

PCI Express 4.0 x4 electrical 32° to 158° F (0° to 70° C)

Operating Temperature
Performance

Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z	Tur	bo	2TB		
2	280	PC	le-4x4	TLC	SSD

Capacity2TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB

PCIe

M.2

NVMe

3D TLC

Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Capacity
Protocol
Form Factor
Controller
NAND Type



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

600TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365 Nο

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 700K IOPS* **Random Write** up to 700K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

Z Turbo 4TB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD** Capacity 4TB **Protocol** PCIe **Form Factor** M.2 NVMe Controller **NAND Type** 3D TI C

Endurance 600TBW (TB Written)

No

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

PCI Express 4.0 x4 electrical

Operating Temperature Performance

32° to 158° F (0° to 70° C)

Sequential Read Sequential Write

up to 5000MB/s* up to 700K IOPS*

up to 6500MB/s*

Random Read Random Write

up to 700K IOPS*

Self-Encrypting Drive

Support

OPAL 2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

Performance PCIe SSDs for HP Dual Pro Carrier

HP Z Turbo Drive Dual Pro 512GB SSD

512GB Capacity PCle Protocol **Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

PCI Express 4.0 x4 electrical

Interface **Operating Temperature** 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6400MB/s*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Sequential Write up to 3400MB/s*

Random Read up to 600K IOPS*

Random Write up to 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z	Turbo	Drive
Dual	Pro 1 1	TB SSD

capacity	IIB
Protocol	PCIe
Form Factor	M.2
Controller	NVMe
NAND Type	3D TLC

Endurance 400TBW (TB Written)

Nο

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

Performance

PCI Express 4.0 x4 electrical 32° to 158° F (0° to 70° C)

Operating Temperature

Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

ΗP	Z	Turl	bo	Dı	rive
Du	al	Pro	2 T	В	SSD

Capacity	2TB
Protocol	PCIe
Form Factor	M.2
Controller	NVMe
NAND Type	3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

Performance

PCI Express 4.0 x4 electrical

Operating Temperature 32° to 158° F (0° to 70° C)

No

Sequential Read up to 6500MB/s*
Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drive	Capacity	4TB
Dual Pro 4TB SSD	Protocol	PCle
	Form Factor	M.2



^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Controller NVMe NAND Type 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

SATA Hard Drives for HP Workstations

1TB 7200RPM SATA 3.5in Capacity Enterprise HDD Protocol

Capacity1TBProtocolSATAForm Factor3.5"ControllerAHCIReliability2.0M hoursRated Power On Hours8760/yrAnnualized Failure Rate<0.62%</th>

(based on Rated POH)
Rated for 24/7/365

operation

Height 1 in: 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in: 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

YES

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 128MB Cache Adaptive

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.32 ms *Full Stroke7.45 ms *14.2 ms *

Rotational Speed 7,200 rpm **Logical Blocks** 1,953,525,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB 7200RPM SATA 3.5in Capacity

2TB

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Enterprise HDD	Protocol	SATA
	Form Factor	3.5"
	Controller	AHCI
	Reliability	2.0M ho

ours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** < 0.62%

(based on Rated POH)

Rated for 24/7/365 YES

operation

Height 1 in: 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in: 10.17 cm

Up to 600MB/s *

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 128MB Cache Adaptive

Seek Time (typical reads, **Single Track** 0.7 ms * includes controller Average 8.5 ms * overhead, including **Full Stroke** 15.7 ms * settling)

Rotational Speed 7.200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s* **Sequential Write** up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB 7200 RPM SATA 3.5in	Capacity	4TB
Enterprise HDD	Protocol	SATA
	Form Factor	3.5"
	Controller	AHCI
	Reliability	2.0M hours
	Rated Power On Hours	8760/vr

Annualized Failure Rate (based on Rated POH)

Rated for 24/7/365

operation

YES

<0.62%

Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 256MB Cache Adaptive



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Seek Time (typical reads, Single Track $0.7 \, \text{ms} *$ includes controller Average 8.5 ms * overhead, including **Full Stroke** 15.7 ms * settling)

Rotational Speed 7.200 rpm **Logical Blocks** 7,814,037,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s* **Sequential Write** up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

BTB 7200RPM SATA 3.5ir	1
Enterprise HDD	

Capacity **Protocol** SATA **Form Factor** 3.5" Controller **AHCI** Reliability 2.0M hours **Rated Power On Hours** 8760/vr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365 YES

operation

Height 1 in: 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in: 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

0.7 ms *

8.5 ms *

15.7 ms *

Buffer 256MB Cache Adaptive

Seek Time (typical reads, **Single Track** includes controller Average overhead, including **Full Stroke** settling)

Rotational Speed 7,200 rpm **Logical Blocks** 15.628.053.168

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s* **Sequential Write** up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

12TB 7200 RPM SATA-6G Capacity 3.5in Enterprise HDD

12TB Protocol **SATA Form Factor** 3.5" Controller AHCI Reliability 2.0M hours



^{*}Actual performance may vary.

^{*}Actual performance may vary.

0.7 ms *

8.5 ms *

15.7 ms *

Technical Specifications - Hard Drives

Rated Power On Hours 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365 operation

YES

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Rotational Speed

Logical Blocks

Up to 600MB/s *

256MB Adaptive

Cache Adaptive
Seek Time (typical reads, includes controller overhead, including Full Stroke

Adaptive
Adaptive
Average
Full Stroke

settling)

Buffer

7,200 rpm 23,437,770,752

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

^{*}Actual performance may vary.

Technical Specifications - Graphics

GRAPHICS

NVIDIA® RTX™ 6000 Ada Form Factor

48GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Max Power Consumption Power: 300 Watts

Cooling: Active

GPU Memory 48GB GDDR6 memory ECC

Memory Bandwidth: Up to 960 GB/s

Memory Width: 384 bits

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Maximum Resolution 7680x4320 @ 120Hz

Bus Type PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX™ A6000

48GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Max Power Consumption Power: 300 Watts

Cooling: Active

GPU Memory 48GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Svnc

Requires 8-pin auxiliary power

Maximum Resolution

Bus Type

7680x4320 @ 120Hz PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11

Windows 10 Linux® 64-bit

NVIDIA® RTX™ A5000

24GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Max Power Consumption Power: 230W

Cooling: Active

GPU Memory 24GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution 7680x4320 @ 120Hz



Technical Specifications - Graphics

Bus Type PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX A4500

20GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Max Power Consumption Power: 200W

Cooling: Active

20GB GDDR6 memory **GPU Memory**

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution

Bus Type

7680x4320@120Hz PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® RTX A4000

16GB

Full-Height Single Slot (4.4" Height x 9.5" Length) **Form Factor**

Weight: 500 grams

Max Power Consumption Power: 140W

Cooling: Active

16GB GDDR6 memory **GPU Memory**

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

4x DisplayPort 1.4a Connectors

Quadro Sync II connector

Stereo Sync

Requires 6-pin auxiliary power

Maximum Resolution

7680x4320@120Hz **Bus Type**

Available Graphics

Drivers

PCI Express 4.0 x16

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® RTX A2000

12GB

Form Factor Half-Height Dual Slot (2.713"

Height x 6.6" Length)

Weight: 306 grams

Max Power Consumption Power: 70W

Cooling: Active

12GB GDDR6 memory **GPU Memory**

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192 bit

Connectors 4x mini-DisplayPort 1.4a

Maximum Resolution 7680x4320 @ 120Hz

Technical Specifications - Graphics

Bus Type PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® T1000 8GB Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors4x mini-DisplayPort 1.4aMaximum Resolution7680x4320 @ 120HzBus TypePCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® T1000 4GB Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors4x mini-DisplayPort 1.4aMaximum Resolution7680x4320 @ 120HzBus TypePCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® T400 4GB

Graphics

Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 123.5 grams

Max Power Consumption Power: 30W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 80 GB/s

Memory Width: 64 bit

Connectors3x mini-DisplayPort 1.4aMaximum Resolution7680x4320 @ 120HzBus TypePCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

Technical Specifications - Graphics

AMD® Radeon™ Pro W6800 32GB

Full-Height Dual Slot (4.4" Height x 10.5" Length) Form Factor

Weight: 850 grams

Max Power Consumption Power: 261W

Cooling: Active

32GB GDDR6 memory **GPU Memory**

Memory Bandwidth: Up to 512 GB/s

Memory Width: 256 bit

7680x4320 @ 60Hz

Connectors 6x mini-DisplayPort 1.4

Requires 8-pin+6-pin auxiliary power

Maximum Resolution

Bus Type PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

AMD® Radeon™ RX 6700XT 12GB

Form Factor Full-Height Dual Slot (4.30" Height x 10.0" Length)

Weight: 684 grams

Max Power Consumption Power: 238W

Cooling: Active

12GB GDDR6 memory **GPU Memory**

Memory Bandwidth: Up to 384 GB/s

Memory Width: 192 bit

4x DisplayPort 1.4 **Connectors**

1x HDMI

Requires 8-pin+6-pin auxiliary power

Maximum Resolution

Bus Type

7680x4320 @ 60Hz PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

AMD® Radeon™ Pro W66008GB

Form Factor Full-Height Single Slot (4.38" Height x 9.50" Length)

Weight: 132.6 grams

Max Power Consumption Power: 122W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 224 GB/s

Memory Width: 128 bit

Connectors 4x DisplayPort 1.4

Requires 6-pin auxiliary power

Maximum Resolution

7680x4320 @ 60Hz **Bus Type**

Available Graphics

Drivers

PCI Express 4.0 x16 (x8 electrical)

Windows 10 Linux® 64-bit

Windows 11

AMD® Radeon™ RX 6400 Form Factor

4GB

Half-Height Single Slot (4.4"

Height x 10.5" Length)

Weight: 155 grams



Technical Specifications - Graphics

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Memory Width:

Connectors 1x DisplayPort 1.4a

1x HDMI

Maximum Resolution7680x4320 @ 60HzBus TypePCI Express 4.0 x4

Available Graphics

Drivers Windows 10

Linux® 64-bit

Windows 11

Intel® Arc Pro A40 6GB

Form Factor Half-Height Single Slot (2.7"

Height x 6.6" Length) Weight: 220 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: 192GB

Memory Width: 96 bit

Connectors4x mini- DisplayPort 1.4Maximum Resolution7680x4320 @ 60HzBus TypePCI Express 4.0 x8

Available Graphics

Drivers Windows 10

Notes for all graphics cards:

• Some graphics and GPU compute cards can consume a great deal of power, thus combinations of cards with other components may exceed a particular power supply's output capability.

Windows 11

- Some graphics and GPU compute cards require supplemental power cables.
- Not all chassis/PSU configurations have enough supplemental power cables of the correct type for all graphics configurations.

Refer to the Power Supply section within Overview for more information.



Technical Specifications - Optical and Removable Storage

OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim Blu-Ray Writer **Description** 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types BD-ROM

BD-R BD-RE DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Blu-ray 25 GB (single-layer)

50 GB (dual-layer) 100/128 GB (BDXL)

Full Stroke DVD < 230 ms (seek)
Full Stroke CD < 220 ms (seek)

Blu-ray< 230 ms (seek) (Full Stroke Blu-ray)</th>Startup Time(Time to drive ready from tray loading)

BD-ROM (SL/DL) 25S / 28S BD-R (SL/DL) 25S / 28S BD-RE (SL/DL) 25S / 28S DVD-ROM (SL/DL) 18S / 18S DVD-R (SL/DL) 25S / 25S

DVD-RW 25S

DVD+R (SL/DL) 25S / 25S

DVD+RW 25S CD-ROM 15S

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Blu-ray BD-ROM Up to 6X

BD-ROM DL Up to 6X
BD-R Up to 6X
BD-R DL Up to 6X
BD-R Up to 6X
BD-RE SL/DL Up to 6X

Technical Specifications - Optical and Removable Storage

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p **DC Current** 5 VDC -900 mA typical, 2000mA

maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity 10% to 80% Maximum Wet Bulb 84° F (29° C)

Temperature

Operating Systems
Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit, Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

NOTE: HD-DVD disks cannot be played on the DVD-ROM drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. Flawless playback on all systems is not guaranteed.

HP 9.5mm Slim DVD Writer **Description** 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Full Stroke DVD < 200 ms (seek)
Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X

Technical Specifications - Optical and Removable Storage

DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-**Relative Humidity** 10% to 80% condensing)

Maximum Wet Bulb 84° F (29° C)

Temperature

Operating Systems Windows 11, Windows 10, Windows 7 Professional 64-bit. Supported

Windows Vista Business 64*. Windows 2000.

Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

* No driver is required for this device. Native support is provided by the

operating system

Kit Contents HP SATA DVD Writer drive, installation guide.

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Laver discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD-ROM Description 9.5mm height, tray-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

CD-ROM Mode 1 < 110 ms (typical)
Full Stroke DVD < 230 ms (typical)
Full Stroke CD < 220 ms (typical)

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems

Supported

Windows 11, Windows 10, Windows 8.1, Windows 7 Professional 64-bit

Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25"" ODD Bay adapter/carrier, slim SATA

data/power cable, installation guide

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

NVIDIA® Mellanox® Connect ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

Connector 2 x SFP28 Transceiver Cage (Dual Port)*

Depends on transceiver pairing. Typically OM4 or higher MMF LC fiber optic

cabling with LC SFP28 Transceivers.

Controller ConnectX6-DX

Memory 256Mbit SPI Quad Flash Device

Data Rates Supported 1/10/25GbE

Compliance – IEEE 802.3by 25 Gigabit Ethernet

– IEEE 802.3ae 10 Gigabit Ethernet

- IEEE 802.3ap based auto-negotiation and KR startup

IEEE 802.3ad, 802.1AX Link AggregationIEEE 802.1Q, 802.1P VLAN tags and priority

IEEE 802.1Qau (QCN)
Congestion Notification
IEEE 802.1Qaz (ETS)
IEEE 802.1Qbb (PFC)
IEEE 802.1Qbg
IEEE 1588v2

Jumbo frame support (9.6KB)Safety: CB/cTUVus/CEEMC: CE/FCC/VCCI/RCM

- RoHS Compliant

- KCC

- CAN ICES-3 (B)

- NM EN 55035/55032 (Morocco)

- UKCA

Bus Architecture PCIe Gen 4 x8

Data Transfer Mode PCI Express - stores and accesses Ethernet fabric connection information

and packet data

Power Requirements 11.5 Watts (typical)

Network Transfer Rate 1Gbps, 10Gbps, 25Gbps

NOTE: Network Transfer Rate depends on transceiver model.*

Kit Contents NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

*3rd party transceivers sold separately. You must have a transceiver installed in order to connect this card to a network.

Intel® X550 10GBASE-T Dual Port NIC **Connector** 2 x RJ-45

Cabling Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6 (or higher) for 10Gbps up to 55m Cat6a (or higher) for 10Gbps up to 100m

Controller Intel X550-AT2

Memory Jumbo Frames up to 15.5KB, 64 Tx and 64Rx Queues per port, 160KB/port

of programmable memory transmit buffers

Data Rates Supported

100Mbps (BASE-TX), 1Gbps (BASE-T, 2.5Gbps, 5Gbps, 10Gbps

Compliance

802.1q (VLAN), 802.1Qbb, 802.1p, 802.1Qaz

Bus Architecture PCIe 3x4

Technical Specifications - Networking and Communications

Data Transfer Mode PCIe Gen 3 x4 based interface

Power Requirements 3.9W at 100Mbps

5.5W at 1Gbps 11.2W at 10Gbps

Boot ROM Support Yes

Network Transfer Mode Auto negotiation between 1GbE, 2.5GbE, 5GbE and 10GbE

Management Capabilities DMI 2.0 Support, Windows Management Instrumentation (WMI) and SNMP,

PXE 2.0 through boot ROM, Multi-mode I/O Virtualization, VxLAN, VMDq,

VLAN support with VLAN tag insertion

Kit Contents Intel® X550 10GBASE-T Dual Port NIC

Intel® 1225-T1 Single Port 2.5GbE PCIe NIC **Connector** RJ-45 (Single Port)

CablingCat5e (or better) up to 100mControllerIntel® Ethernet I225 Controller

Memory Jumbo Frames up to 9.5KB, 4 Tx and Rx Queues,

Data Rates Supported 2.5GbE, 1GbE, 100MbE, 10MbE

Compliance IEEE 802.3 auto negotiation, 802.3x, 802.3z

Bus Architecture PCle Gen 3.1x1

Data Transfer Mode PCIe-based interface for active state operation

Power Requirements 1.9 Watts (typical)

Management Capabilities WOL, PXE 2.1, Power Management Protocol Offload (proxying), MAC Power

Management, Active State Power Management,

Kit Contents Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached

and Low-profile bracket included

Product Literature

Intel® Ethernet I350-T4 V2 4-Port 1Gb NIC

Connector 4x RJ-45 (Quad Port)

Cabling Cat3 (or higher) for 10Mbps

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Controller Intel® 1350

Memory Jumbo Frames up to 9.5KB, 8 Tx/Rx Queue pairs per port, Main Internal

memory is Error Code Correcting

Data Rates Supported

10Mbps, 100Mbps, 1Gbps

Compliance

IEEE 802.3 auto negotiation, 802.3, 802.3u, 802.3ab, 802.3x, 802.3z,

IEEE1588 protocol and 802.1AS implementation, 802.3az EEE

Bus Architecture PCI Express 2.1 x4

Data Transfer Mode PCIe-based interface for active state operation

Power Requirements 5W

Network Transfer Mode Multi-speed, full, and half-duplex

Network Transfer Rate 10BASE-T

100BASE-TX 1000BASE-T

Management Capabilities WOL, PXE 2.1, UEFI, Power Management Protocol Offload (proxying), MAC

Power Management, Active State Power Management, VLAN, ACPI

Kit Contents Intel® Ethernet I350-T4V2 4-Port 1Gb NIC with full-height bracket installed

Technical Specifications - Networking and Communications

Low-profile bracket included

Allied Telesis AT-2911T/2-901 Dual Port **1GbE NIC**

Connector 2 x RJ-45 (Dual Port) Cabling Cat3 (or higher) for 10Mbps

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Memory 17 Rx and 16 Tx queues **Data Rates Supported** 10/100/1000 Mbps

Compliance IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC),

IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation), IEEE 802.3ab

(10/100/1000T)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCIe 2x1

Data Transfer Mode PCIe-based interface **Power Requirements** 2.4 Watts (typical)

Management Capabilities VLAN support, Link aggregation LACP, Link aggregation smart switch,

Failover, Smart Load Balancing (SLB), iSCSI boot support, Windows

Management Instrumentation (WMI), PXE 2.1, SNMP

Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC with low-profile bracket **Kit Contents**

attached and standard bracket included

Allies Telesis AT-2914SX/LC 1GB LC Fiber NIC

LC Fiber (Single Port) Connector

Cabling 50/125 µm (core/cladding) multimode fiber optic cable up to 500m

62.5/125 µm (core/cladding) multimode fiber optic cable up to 220m

Memory Jumbo Frames up to 9.6KB

Data Rates Supported

1000SX (1GbE Fiber at 850nm Wavelength)

IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC), Compliance

IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE

802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCle x1

Data Transfer Mode PCIe-based interface **Power Requirements** 1.5 Watts (typical)

Network Transfer Rate 1000SX only (1GbE Fiber at 850nm Wavelength)

Management Capabilities UEFI, Smart Load Balancing and failover, Link aggregation (IEEE802.3ad),

Generic trunking (FEC/GEC) / IEEE 802.3ad-draft static, VLAN Support

Allied Telesis AT-2914SX/LC 1GB LC Fiber NIC with low-profile bracket **Kit Contents**

attached and standard height bracket included

HP 10GBase-T Flex Port Connector **RJ-45**

> Cabling Twisted Pair Cabling, up to 100 meter

Controller Marvell AQC113C

128KB Tx Buffer, 192KB Rx Buffer on-chip Memory **Data Rates Supported** 10/100/1000 Mbps and 2.5/5/10 Gbps

Compliance 802.3 - 2018, 802.1AS-2011

Technical Specifications - Networking and Communications

Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (S0 state) and SMBus for

host and management traffic

Power Requirement Requires 0.7V VDD, 1V, and 2V for analog, 3.3V for VDDIO

Boot ROM Support Yes

Network Transfer Mode Full-duplex
Network Transfer Rate 10GBASE-T

5GBASE-T 2.5GBASE-T 1000BASE-T 100BASE-TX 10BASE-Te

Management Capabilities WOL, PXE, UEFI,

Kit Contents HP 10GBase-T Flex Port NIC Module

HP 2.5GbE LAN Flex Port Connector RJ45 (Single Port)

Cabling Copper twisted pair, Cat5e up to 100 meters

Controller Intel® I225-V

Memory 4 Tx and 4 Rx Queues, Jumbo Frames up to 9KB and without TSN

Data Rates Supported 10/100/1000Mbps and 2.5Gbps BASE-T

Compliance IEEE 802.3, 802.3u (auto-negotiation), 802.3ab, 1588, 802.1AS-Rev,

802.1Qav, 802.1Qbu, 802.1Qbv, 802.3br, 802.3az

Bus Architecture PCIe G2x1

Data Transfer Mode PCIe-based interface for active state operation (S0 state) and SMBus for

host and management traffic (Sx low power state)

Power Requirements 2.2 Watts

Network Transfer Mode Automatic link configuration for speed duplex and flow control

Network Transfer Rate 2500BASE-T

1000BASE-T

100BASE-TX (Half-duplex supported) 10BASE-Te (Half-duplex supported)

Management Capabilities WOL, PXE, UEFI, Intel vPro® support with appropriate Intel Chipset, Error

Correcting Memory in packet buffers, UDP/TCP/IP Checksum Offload, SCTP

receive and transmit integrity offload

Kit Contents HP 2.5GbE LAN Flex Port Networking Interface Card

HP 1GbE Fiber LC Single Flex Port

Connector LC (Little Connector) Fiber (Single Port)

Cabling LC Fiber Cabling
Controller AT-29M2

Data Rates Supported 1GBASE-SX

Bus Architecture USB 3.1G1

Power Requirements Up to 3.3 Watts

Network Transfer Mode 1GBASE-SX

Network Transfer Rate 1GBASE-SX

Management Capabilities Wake on LAN, Digital Diagnostic Monitoring

Technical Specifications - Networking and Communications

Kit Contents HP 1GbE Fiber LC Single Flex Port NIC

HP Flex 1GbE Single Port Connector

RJ45 (Single Port)

1GbE over Category 5e (or better) up to 100m Cabling

Controller Realtek RTL8153 **Data Rates Supported** 10/100/1000 Mbps **Bus Architecture** USB3.1G1. USB2

Power Requirements Requires 3.3V (integrated regulators for core Vdc)

Network Transfer Mode Full-duplex: Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

> 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities Wake on LAN, PXE, UEFI

Kit Contents HP 1GbE Single Flex Port

Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 Flex Port **NIC** with Internal Antennae

Connector Wireless Cabling N/A

Controller Intel® AX210

Data Rates Supported

Wi-Fi 6 (2.4GHz/5GHz)

Compliance

Compliance

Wi-Fi Alliance* Wi-Fi Alliance CERTIFIED 6, WiFi CERTIFIED a/b/g/n/ac, WMM, WMM-Power Save, WPA2, WPA3, Wi-Fi Direct, and Wi-Fi Agile

Multiband

IEEE WLAN Standard 802.11-2016, 802.11a, b, d, e, g, h, l, k, n, r, u, v, w, ac,

and ax, Bluetooth® 5.2

Bus Architecture PCIe G3x1 for WLAN, USB3.1G1 for BT

Management Capabilities Authentication Protocols: 802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 -

MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')

Encryption: 128-bit AES-CCMP, 256-bit AES-GCMP

UEFI

Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 Flex Port NIC **Kit Contents**

Installation Instructions

* Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

Intel® AX210 Wi-Fi 6E non-vPro + Bluetooth® 5.2 with External **Antennae WLAN**

Connector Wireless N/A Cabling

Intel® AX210 Controller

Data Rates Supported

Wi-Fi 6e (2.4GHz/5GHz/6GHz)

Wi-Fi Alliance* Wi-Fi Alliance CERTIFIED 6, WiFi CERTIFIED a/b/g/n/ac. WMM, WMM-Power Save, WPA2, WPA3, Wi-Fi Direct, and Wi-Fi Agile

Multiband

IEEE WLAN Standard 802.11-2016, 802.11a, b, d, e, g, h, l, k, n, r, u, v, w, ac,

and ax, Bluetooth® 5.2

Bus Architecture PCIe G3x1 for WLAN, USB3.1G1 for BT



Technical Specifications - Networking and Communications

Management Capabilities Authentication Protocols: 802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 -

MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA') Encryption: 128-bit AES-CCMP, 256-bit AES-GCMP

UEFI

Kit Contents Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 PCIe NIC

External Dipole Antenna Installation Instructions

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Date of change:	Version History:		Description of change:
March 1, 2023	From v1 to v2	Changed	Optical and Removable Storage, Networking and Communications sections and Changed Format
March 30, 2023	From v2 to v3	Changed	lmage page 1
April 1, 2023	From v3 to v4	Changed	Format
April 6, 2023	From v4 to v5	Changed	Processors section



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